

	Type	Hits	Search Text	DBs
1	IS&R	2	("5236118").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	IS&R	0	("stmnear15handler").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	19	stm near15 handler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	IS&R	839	(361/807).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	12	("4646435"   "5207465"   "5215472"   "5302853"   "5467526"   "5526974"   "5953816"   "5983477"   "5984693"   "5991161"   "6191480"   "6386432").PN.	USPAT
6	IS&R	1723	(29/834-838,844-845).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	1470	((29/834-838,844-845).CCLS.) and @ad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	351	((29/834-838,844-845).CCLS.) and @rlad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	1512	((29/834-838,844-845).CCLS.) and @ad<20010830 ((29/834-838,844-845).CCLS.) and @rlad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	52	((pick near2 place) near15 pins) same align\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	3082	align\$4 near15 chip near15 (board or pcb or die or carrier or base)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	187	align\$4 near15 chip near15 (board or pcb or die or carrier or base) near15 (pin or pins)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	483	(engag\$4 or pick\$) near15 chip near15 (pin or pins)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	133814	align\$4 near15 (board or pcb or die or carrier or base)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	99	((engag\$4 or pick\$) near15 chip near15 (pin or pins)) and (align\$4 near15 (board or pcb or die or carrier or base))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
16	IS&R	3180	(29/739-740,752).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17	BRS	2863	((29/739-740,752).CCLS.) and @ad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18	BRS	287	((29/739-740,752).CCLS.) and @rlad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	BRS	2916	((29/739-740,752).CCLS.) and @rlad<20010830) ((29/739-740,752).CCLS.) and @ad<20010830)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	BRS	2657	((29/739-740,752).CCLS.) and @rlad<20010830) ((29/739-740,752).CCLS.) and @ad<20010830)) not (((29/834-838,844-845).CCLS.) and @ad<20010830) (((29/834-838,844-845).CCLS.) and @rlad<20010830))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	BRS	272	pick\$4 and align\$4 and ((((29/739-740,752).CCLS.) and @rlad<20010830) (((29/739-740,752).CCLS.) and @ad<20010830)) not (((29/834-838,844-845).CCLS.) and @ad<20010830) (((29/834-838,844-845).CCLS.) and @rlad<20010830)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	2657	((29/739-740,752).CCLS.) and @rlad<20010830) ((29/739-740,752).CCLS.) and @ad<20010830)) not (((29/834-838,844-845).CCLS.) and @ad<20010830) (((29/834-838,844-845).CCLS.) and @rlad<20010830))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
23	BRS	675	align\$4 and ((((29/739-740,752).CCLS.) and @rlad<20010830) (((29/739-740,752).CCLS.) and @ad<20010830)) not (((29/834-838,844-845).CCLS.) and @ad<20010830) (((29/834-838,844-845).CCLS.) and @rlad<20010830)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
24	BRS	156	semiconductor and (align\$4 and (((((29/739-740,752).CCLS.) and @rlad<20010830) (((29/739-740,752).CCLS.) and @ad<20010830)) not (((29/834-838,844-845).CCLS.) and @ad<20010830) (((29/834-838,844-845).CCLS.) and @rlad<20010830))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
25	IS&R	4433	(438/106-107,121,125).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
26	BRS	212581 63	@rlad<20010830 or @ad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
27	BRS	3611	((438/106-107,121,125).CCLS.) and (@rlad<20010830 or @ad<20010830 )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
28	BRS	2864	semiconductor and (((438/106-107,121,125).CCLS.) and (@rlad<20010830 or @ad<20010830 ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
29	BRS	1255	align\$4 and (((438/106-107,121,125).CCLS.) and (@rlad<20010830 or @ad<20010830 ))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
30	BRS	145	pick\$4 and (align\$4 and (((438/106-107,121,125).CCLS.) and (@rlad<20010830 or @ad<20010830 )))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
31	BRS	194513	(position\$4 or align\$4 or guid\$4) near2 (pin or pins)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
32	BRS	535	(semiconductor or chip or (circuit adj board) or pcb) and (align\$4 and (((((29/739-740,752).CCLS.) and @rlad<20010830) (((29/739-740,752).CCLS.) and @ad<20010830)) not (((29/834-838,844-845).CCLS.) and @ad<20010830) (((29/834-838,844-845).CCLS.) and @rlad<20010830))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
33	BRS	23355	(semiconductor or chip or (circuit adj board) or pcb) and ((position\$4 or align\$4 or guid\$4) near2 (pin or pins))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
34	BRS	16871	(pick\$4 or hold\$4) near15 ((position\$4 or align\$4 or guid\$4) near2 (pin or pins))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
35	BRS	2343	((semiconductor or chip or ((circuit adj board) or pcb) and ((pick\$4 or hold\$4) near15 ((position\$4 or align\$4 or guid\$4) near2 (pin or pins))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
36	BRS	438	((semiconductor or chip) and ((circuit adj board) or pcb) and ((pick\$4 or hold\$4) near15 ((position\$4 or align\$4 or guid\$4) near2 (pin or pins))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
37	BRS	210903 53	((semiconductor or chip) and ((circuit adj board) or pcb) and ((pick\$4 or hold\$4) near15 ((position\$4 or align\$4 or guid\$4) near2 (pin or pins)))) and @rlad<20010830 or @ad<20010830	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
38	BRS	385	((semiconductor or chip) and ((circuit adj board) or pcb) and ((pick\$4 or hold\$4) near15 ((position\$4 or align\$4 or guid\$4) near2 (pin or pins)))) and (@rlad<20010830 or @ad<20010830)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
39	BRS	135	connector near3 semiconductor near15 (circuit adj board or pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
40	BRS	141323	circuit adj board and ((guide adj (pin or pins)) near15 epoxy or plastic or metal or metallic or conductive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
41	BRS	165	circuit adj board and ((guide adj (pin or pins)) near15 (epoxy or plastic or metal or metallic or conductive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
42	BRS	121	circuit adj board near2 stiffener	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
43	BRS	2	((flexible adj substrate) near2 stiffener) near15 (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
44	BRS	190	(flexible adj substrate) near2 (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
45	BRS	242	("4066839" "4514750" "4589010"  "4701781" "4801997" "5114880"  "5468991" "5530295" "5986885"  "6169323").PN	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
46	IS&R	2	("5987742").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
47	IS&R	0	("throughadjhole").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
48	BRS	324411	through adj hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
49	BRS	21354	chip and (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
50	BRS	2146	flexible and solder and (chip and (through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
51	BRS	1445	epoxy and (flexible and solder and (chip and (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
52	BRS	424	pcb and (flexible and solder and (chip and (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
53	BRS	0	(punch adj assembly) near15 (solder adj balls) near15 (electrically)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
54	BRS	2	(punch adj assembly) near15 (solder adj balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
55	BRS	2	(punch adj assembly) same (solder adj balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
56	BRS	3	(punch adj assembly) and (solder adj balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
57	IS&R	8	(("5525834") or ("5409865") or ("5397921") or ("5386341")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
58	IS&R	4	("2752580").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB